

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC2460CMS#TRPBF

(Engineering Calculation)

MSOP

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TOTAL MASS (g): 0.035901

| COMPONENT MATERIAL | VENDOR/INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL Pkg. | | |
|--------------------------------|----------------------------------|--------------------------|-------------------------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001287 | 1000000 | 25846.5589328 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013845 | 975000 | 385643.59375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000341 | 24000 | 9498.3339375 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 111.417427063 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000010 | 700 | 278.543379102 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead Frame Total: | | | | 0.014290 | 1000000 | 398531.90625 |
| | | Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 |
| Exter. Plating Sn | 7440-31-5 | | | 0.000710 | 1000000 | 19777.2890625 | | |
| External Plating Total: | | | | | | 0.000710 | 1000000 | 19777.2890625 |
| Inter. Plating Ni | 7440-02-0 | | | 0.000000 | 0 | 0 | | |
| Inter. Plating Ag | 7440-22-4 | | | 0.000086 | 1000000 | 2395.47485352 | | |
| Internal Plating Total: | | | | | | 0.000086 | 1000000 | 2395.47485352 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000542 | 750000 | 15097.0625 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000181 | 250000 | 581.63867188 | | |
| | | Die Attach Total: | | | | 0.000723 | 1000000 | 20126.6992188 |
| | | Encapsulation | MULTIAROMATIC RESIN BESS-FREE | Resin (EP) | 0.002439 | 130000 | 67936.78125 | |
| | | | | Bromine (Br) | 40093-93-8 | 0.000000 | 0 | 0 |
| Silica (SiO2) | 60676-86-0 | | | 0.015571 | 830000 | 433720.1875 | | |
| Antimony Trioxide (Sb2O3) | 1309-64-4 | | | 0.000000 | 0 | 0 | | |
| Metal Hydroxide | | | | 0.000657 | 35000 | 18300.3144531 | | |
| Carbon Black (C) | 1333-86-4 | | | 0.000094 | 5000 | 2618.30981445 | | |
| Encapsulation Total: | | | | | | 0.018761 | 1000000 | 522575.625 |
| Lead Wire Estimated | AFW/TANAKA/Kn | Gold (Au) | 7440-57-5 | 0.000134 | 1000000 | 3722.48413086 | | |

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